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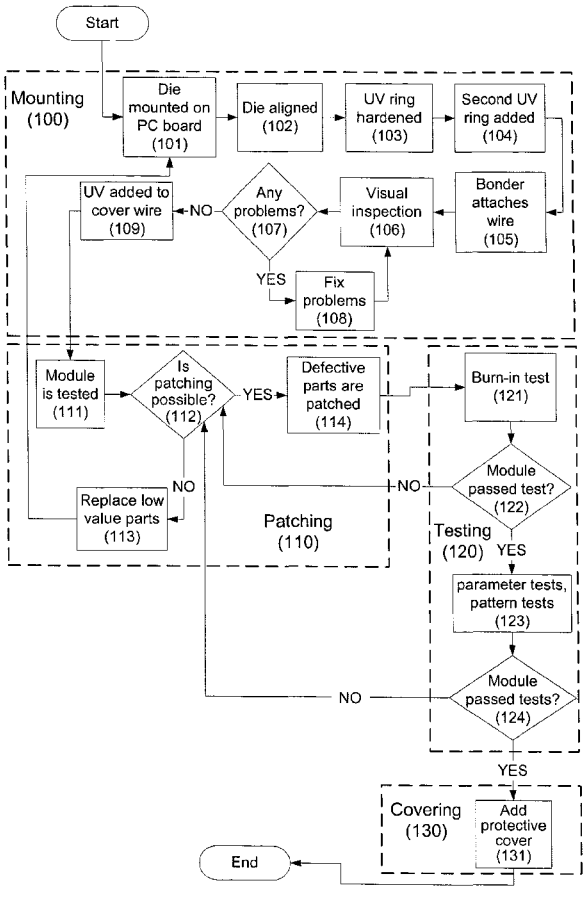
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(54) Title: METHODS AND APPARATUS FOR FABRICATING CHIP-ON-BOARD MODULES



(57) Abstract: A method of assembling a Chip-on-Board memory module as shown in Fig. 1, the method may be divided into several area or steps, mounting (step 100), patching (step 110), testing (step 120), and covering (step 130). During mounting (step 100), preferably, at least one unpackaged chip is mounted on a printing circuit board. In some embodiments, a selectively settable material may used to mount unpackaged memory parts. When mounting die on PC (step 101), a ring of selectively settable material is preferably used to surround the die and hold the die in place. Once mounted the alignment of each unpackaged chip may be adjusted (step 102), after which the ring selectively settable material disposed around the chip is cured or hardened (step 103). The hardened ring around each die keeps the die in place. In some embodiments, the ring is higher than the die it surround to facilitate the addition of bond wires.

WO 03/073357 A1

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